1. A switching device comprising:

a first conductive terminal;

a second conductive terminal; and

a conductive pill that moves between an open position and a closed position wherein said first and said second terminals are shorted in said closed position, wherein said first and said second terminals are not shorted in said open position, and wherein said conductive pill comprises a conductive loaded, resin-based material comprising conductive materials in a base resin host.

2.The device according to Claim 1 wherein the ratio, by weight, of said conductive materials to said resin host is between about 0.20 and about 0.40.

3.The device according to Claim 1 wherein said conductive materials comprise metal powder.

4.The device according to Claim 4 wherein said metal powder is nickel, copper, silver, or is a material plated with nickel, copper, or silver.

5.The device according to Claim 3 wherein said metal powder comprises a diameter of between about 3 μm and about 12 μm.

6.The device according to Claim 1 wherein said conductive materials comprise non-metal powder.

7.The device according to Claim 6 wherein said non-metal powder is carbon, graphite, or an amine-based material.

8.The device according to Claim 1 wherein said conductive materials comprise a combination of metal powder and non-metal powder.

9.The device according to Claim 1 wherein said conductive materials comprise micron conductive fiber.

10.The device according to Claim 9 wherein said micron conductive fiber is nickel plated carbon fiber, stainless steel fiber, copper fiber, silver fiber or combinations thereof.

11.The device according to Claim 9 wherein said micron conductive fiber pieces each have a diameter of between about 3 μm and about 12 μm and a length of between about 2 mm and about 14 mm.

12.The device according to Claim 1 wherein said conductive materials comprise a combination of conductive powder and conductive fiber.

13.The device according to Claim 1 wherein at least one of said first and second conductive terminals comprise a conductive loaded, resin-based material comprising conductive materials in a base resin host.

14.The device according to Claim 1 wherein said movable conductive pill is fixably mounted on a keypad.

15.The device according to Claim 14 wherein said keypad is part of an array of keypads on a keyboard device.

16.The device according to Claim 14 wherein said array of keypads comprises a common membrane.

17.The device according to Claim 16 wherein said membrane comprises a conductive loaded, resin-based material comprising conductive materials in a base resin host.

18.The device according to Claim 14 further comprising a pad structure and a spring structure wherein said

conductive pill, said pad structure, and said spring structure all comprise a conductive loaded, resin-based material comprising conductive materials in a base resin host.

19.The device according to Claim 1 wherein said conductive pill rotates about an axis to move between said open and closed positions.

20.The device according to Claim 1 wherein said conductive pill tilts in three dimensions to move between said open and closed positions.

21. A keypad device comprising:

a first conductive terminal;

a second conductive terminal;

a pad structure;

a spring structure; and

a conductive pill that moves between an open position and a closed position wherein said first and said second terminals are shorted in said closed position, wherein said first and said second terminals are not shorted in said open position, and wherein said conductive pill, said pad structure, and said spring structure all comprise a

conductive loaded, resin-based material comprising conductive materials in a base resin host.

22.The device according to Claim 21 wherein the ratio, by weight, of said conductive materials to said resin host is between about 0.20 and about 0.40.

23.The device according to Claim 21 wherein said conductive materials comprise metal powder.

24.The device according to Claim 21 wherein said conductive materials comprise non-metal powder.

25.The device according to Claim 24 wherein said non-metal powder is carbon, graphite, or an amine-based material.

26.The device according to Claim 21 wherein said conductive materials comprise a combination of metal powder and non-metal powder.

27.The device according to Claim 21 wherein said conductive materials comprise micron conductive fiber.

28.The device according to Claim 21 wherein said conductive materials comprise a combination of conductive powder and conductive fiber.

29.The device according to Claim 21 wherein at least one of said first and second conductive terminals comprise a conductive loaded, resin-based material comprising conductive materials in a base resin host.

30. A switching device comprising:

a conductive terminal; and

a conductive pill that moves between an open position and a closed position wherein capacitance coupling between said conductive terminal and said conductive pill is greater in said closed position than in said open position, and wherein said conductive pill comprises a conductive loaded, resin-based material comprising conductive materials in a base resin host.

31.The device according to Claim 30 wherein the ratio, by weight, of said conductive materials to said resin host is between about 0.20 and about 0.40.

32.The device according to Claim 30 wherein said conductive

materials comprise metal powder.

33.The device according to Claim 30 wherein said conductive materials comprise non-metal powder.

34.The device according to Claim 33 wherein said non-metal powder is carbon, graphite, or an amine-based material.

35.The device according to Claim 30 wherein said conductive materials comprise a combination of metal powder and non-metal powder.

36.The device according to Claim 30 wherein said conductive materials comprise micron conductive fiber.

37.The device according to Claim 30 wherein said conductive materials comprise a combination of conductive powder and conductive fiber.

38.The device according to Claim 30 wherein said keypad is part of an array of keypads on a keyboard device.

39.The device according to Claim 38 wherein said array of keypads comprises a common membrane.

40.The device according to Claim 39 wherein said membrane comprises a conductive loaded, resin-based material comprising conductive materials in a base resin host.

41.The device according to Claim 38 further comprising a pad structure and a spring structure wherein said conductive pill, said pad structure, and said spring structure all comprise a conductive loaded, resin-based material comprising conductive materials in a base resin host.

42.The device according to Claim 30 wherein said conductive pill rotates about an axis to move between said open and closed positions.

43.The device according to Claim 30 wherein said conductive pill tilts in three dimensions to move between said open and closed positions.

44.A method to form a switching device, said method comprising:

providing a conductive loaded, resin-based material comprising conductive material in a resin-based host; and

molding said conductive loaded, resin-based material into a conductive pill in a switching device wherein said switching device comprises:

a conductive terminal; and

a conductive pill that moves between an open position and a closed position.

45.The method according to Claim 44 wherein the ratio, by weight, of said conductive materials to said resin host is between about 0.20 and about 0.40.

46.The method according to Claim 44 wherein the conductive materials comprise a conductive powder.

47.The method according to Claim 44 wherein said conductive materials comprise a micron conductive fiber.

48.The method according to Claim 44 wherein said conductive materials comprise a combination of conductive powder and conductive fiber.

49.The method according to Claim 44 wherein said molding comprises:

injecting said conductive loaded, resin-based material into a mold;

curing said conductive loaded, resin-based material; and

removing said conductive pill from said mold.

50.The method according to Claim 44 wherein said molding comprises:

injecting said conductive loaded, resin-based material into a chamber;

extruding said conductive loaded, resin-based material out of said chamber through a shaping outlet; and

curing said conductive loaded, resin-based material to form said conductive pill.

51.The method according to Claim 50 wherein said step of extruding forms a rod of said conductive loaded, resin-based material and further comprising cutting said extruded conductive loaded resin-based material to form said conductive pill.

52.The method according to Claim 44 further comprising forming a metal layer around said conductive loaded, resin-based material.

53.The method according to Claim 52 wherein said step of forming a metal layer around said conductive loaded, resin-based material is by plating or by coating said metal layer.